

ABSTRACT

A structure for holding an optical subassembly such as a laser and which minimizes the tilt of the optical subassembly. Pads are placed between the optical subassembly and the housing forming grooves along the inside of the housing and between the pads. The solder for mounting the subassembly to the housing is placed in the grooves. The volume of the solder is chosen so that it does not overflow the grooves. But the solder can be constructed so that its height is greater than the height of the grooves. The optical subassembly is placed against the solder with a downward force and heat is applied to the bottom of the base to melt the solder.